	Material Comp © Copyright 2005. Il international and Par	osition Dee PC, Bannockt	c laration ourn, Illinois. <i>A</i> opyright conve	All rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the encompas	substances ses all lowe	within the er level mat	manufacture erials for wh	er listed it nich the m	em. Note: if anufacturer	the item is an as has engineering	ssembly with lowe responsibility.
1752-21.1	1 IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-05-15			
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item N FCPF400N		n Number Mfr Item Name				Effective Date	Date Version Manufacturing Site		ing Site	V	Weight*	UOM	Unit Type	
			0N60	60 SF2 600V 400mOhm f TO220F			2024-05-15 CNP			2107.333		mg	Each		
/Ianufa	cturing Proccess Information	tion													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		J-STD-020 MSI	Rating	Peak Process Body Temperat		ure Max Time at Peak Tempe		Temperati	ure Numbe	er of Reflow Cy	cles	
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ds 3				
omments	3														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.013	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			А	Lead (Pb)	7439-92-1	7a	3.7522	mg
			Supplier	Tin (Sn)	7440-31-5		0.2007	mg
lead Frame	1289.5	mg	Supplier	Silver (Ag)	7440-22-4		2.579	mg
			Supplier	Iron (Fe)	7439-89-6		1.2895	mg
			Supplier	Copper (Cu)	7440-50-8		1285.2446	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3868	mg
Mold Compound	785.0	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		23.55	mg
			Supplier	Proprietary	Proprietary Data		11.775	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.25	mg
			Supplier	Carbon Black (C)	1333-86-4		3.925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		117.75	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.25	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		549.5	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.12	mg	Supplier	Aluminum (Al)	7429-90-5		2.12	mg